



TMS 2011

140th Annual Meeting & Exhibition

February 27 to March 3, 2011

San Diego Convention Center • San Diego, California USA

7th TMS Lead Free Solder and Interconnect Technology Workshop

Sunday, February 27, 8:30 a.m. to 5:30 p.m.

Overview

This workshop is organized to serve as the industry roadmap for Pb free solder technology in high reliability and consumer electronic packaging and interconnections, with current industry needs and concerns serving as a driving force for research. Through presentations and extensive discussion regarding key topics, this workshop will provide a bridge between companies, academic research groups, national laboratories, and consortia and will lead to the materials science fundamentals necessary for further understanding and future industry applications. Especially this year, the workshop will be focused on new solder alloy compositions and their phase stabilities, as well as the impact of microalloying on solder joint microstructure and mechanical performance.

Topics

- Solder and interconnects in extreme environment
- Future directions in new solder alloy compositions
- Impact of microalloying in Pb-free solders
- Mechanics of deformation in Pb-free solder joints
- Corrosion in Cu pad and Solder joints
- Pb-free board assembly related issues and solutions
- Sn grain orientation effects on long term reliability
- 3D packaging technology and TSV from an industry and academic point of view

Speakers

Stephen Meschter, BAE Systems

Jong-ook Suh, Jet Propulsion Laboratory (NASA JPL)

Keith Sweatman, Nihon Superior

Thomas R. Bieler, Michigan State University

Laura Turbini, Research in motion (RIM)

Eric Chason, Brown University

Young-chang Joo, Seoul national University

Kejun Zhang, Texas Instrument

Fay Hua, Intel

Organizers

Tae-Kyu Lee, Lead organizer, Cisco

Laura Turbini, Research in Motion

John Osenbach, LSI

Polina Snugovsky, Celestica

Albert T. Wu, National Central University

Carol Handwerker, Purdue University

How to Register

Register by February 4, 2011 using the [online registration form](#). Cost is \$15 for full TMS2011 registrants. Non-conference registration fee is \$125.

For More Information

Christina Raabe Eck, *Director of Technical Support Services*

E-mail: raabe@tms.org or Telephone: (724) 776-9000, ext. 212 • (800) 759-4TMS